



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE4678-2LD			<b>Issued</b>	25. September 2017			
<b>MA#</b>	MA001238828							
<b>Package</b>	PG-TSON-10-2			<b>Weight*</b>	31.65 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.689	2.18	2.18	21778	21778
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		105	
	non noble metal	zinc	7440-66-6	0.013	0.04		419	
	non noble metal	iron	7439-89-6	0.265	0.84		8382	
wire	non noble metal	copper	7440-50-8	10.773	34.04	34.93	340358	349264
	non noble metal	copper	7440-50-8	0.056	0.18	0.18	1763	1763
	organic material	carbon black	1333-86-4	0.038	0.12		1206	
encapsulation	plastics	epoxy resin	-	1.966	6.21		62130	
	inorganic material	silicondioxide	60676-86-0	17.087	53.98	60.31	539865	603201
leadfinish	non noble metal	tin	7440-31-5	0.370	1.17	1.17	11693	11693
plating	noble metal	silver	7440-22-4	0.064	0.20	0.20	2030	2030
glue	plastics	epoxy resin	-	0.081	0.26		2568	
	noble metal	silver	7440-22-4	0.244	0.77	1.03	7703	10271
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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